## VOLTAGE: 50 TO 1000V CURRENT: 3.0A

## FEATURES

- Molded case feature for auto insertion
- Glass passivated chip
- High current capability
- Low leakage current
- Fast switching for high efficiency
- High surge capability
- High temperature soldering guaranteed: $250^{\circ} \mathrm{C} / 10 \mathrm{sec} / 0.375^{\prime \prime}(9.5 \mathrm{~mm})$ lead length at 5 lbs tension


## MECHANICAL DATA

- Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
- Case: Molded with UL-94 Class V-O recognized flame retardant epoxy
- Polarity: Color band denotes cathode
- Mounting position: Any


Dimensions in inches and (millimeters)

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Single-phase, half-wave, 60 Hz , resistive or inductive load rating at $25^{\circ} \mathrm{C}$, unless otherwise stated, for capacitive load, derate current by 20\%)

| RATINGS | SYMBOL | $\begin{array}{\|c\|} \hline F R \\ 301 G \end{array}$ | $\begin{array}{\|c} \hline \text { FR } \\ 302 G \end{array}$ | $\begin{array}{\|c\|} \hline \text { FR } \\ 303 G \end{array}$ | $\begin{array}{\|c} \hline \text { FR } \\ 304 G \end{array}$ | $\begin{array}{\|c\|} \hline \text { FR } \\ \text { 305G } \end{array}$ | $\begin{array}{\|c\|} \hline \text { FR } \\ 306 G \end{array}$ | $\begin{array}{\|c\|} \hline \text { FR } \\ 307 G \end{array}$ | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Maximum Repetitive Peak Reverse Voltage | $\mathrm{V}_{\text {RRM }}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | $\mathrm{V}_{\text {RMS }}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | $V_{\text {DC }}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current ( 9.5 mm lead length, at $\mathrm{T}_{\mathrm{a}}=55^{\circ} \mathrm{C}$ ) | $\mathrm{I}_{\mathrm{F}(\mathrm{AV})}$ | 3.0 |  |  |  |  |  |  | A |
| Peak Forward Surge Current (8.3ms single half sine-wave superimposed on rated load) | $\mathrm{I}_{\text {FSM }}$ | 125 |  |  |  |  |  |  | A |
| Maximum Instantaneous Forward Voltage (at rated forward current ) | $\mathrm{V}_{\mathrm{F}}$ | 1.3 |  |  |  |  |  |  | V |
| Maximum DC Reverse Current $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$ <br> (at rated DC blocking voltage) $\mathrm{T}_{\mathrm{a}}=100^{\circ} \mathrm{C}$ | $\mathrm{I}_{\mathrm{R}}$ | $\begin{aligned} & \hline 5.0 \\ & 100 \end{aligned}$ |  |  |  |  |  |  | $\begin{aligned} & \mu \mathrm{A} \\ & \mu \mathrm{~A} \end{aligned}$ |
| Maximum Reverse Recovery Ti (Note 1) | trr | 150 |  |  |  | 250 |  | O | nS |
| Typical Junction Capacitance (Note 2) | $\mathrm{C}_{\mathrm{J}}$ | 40 |  |  |  |  |  |  | pF |
| Typical Thermal Resistance (Note 3) | $\mathrm{R}_{\theta}(\mathrm{ja})$ | 30 |  |  |  |  |  |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Storage and Operation Junction Temperature | $\mathrm{T}_{\mathrm{STG}}, \mathrm{T}_{\mathrm{J}}$ | -65 to +150 |  |  |  |  |  |  | ${ }^{\circ} \mathrm{C}$ |

Note:

1. Reverse recovery condition $\mathrm{I}_{\mathrm{F}}=0.5 \mathrm{~A}, \mathrm{I}_{\mathrm{R}}=1.0 \mathrm{~A}, \mathrm{Irr}=0.25 \mathrm{~A}$
2.Measured at 1.0 MHz and applied voltage of $4.0 \mathrm{~V}_{\mathrm{dc}}$
3.Thermal resistance from junction to ambient at $0.375^{\prime \prime}(9.5 \mathrm{~mm})$ lead length, P.C. board mounted
